SIPMOS® Small-Signal-Transistor

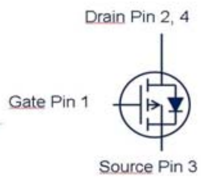
Product Summary

V_{DS}	-60	V
$R_{DS(on),max}$	0.3	Ω
I_D	-1.9	A

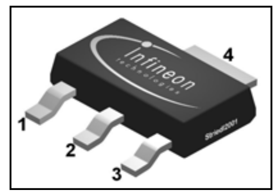
Features

- P-Channel
- Enhancement mode
- Avalanche rated
- d*v*/d*t* rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen-free according to IEC61249-2-21

Halogen-Free AEC Qualified RoHS



PG-SOT223



Type	Package	Tape and reel information	Marking	Lead free	Packing
BSP170P	PG-SOT223	H6327: 1000pcs/reel	BSP170P	Yes	Non Dry

Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
			steady state	
Continuous drain current	I_D	T_A=25 °C	-1.9	A
		T_A=70 °C	-1.5	
Pulsed drain current	$I_{D,pulse}$	T_A=25 °C	-7.6	
Avalanche energy, single pulse	E_{AS}	I_D=1.9 A, R_{GS}=25 Ω	70	mJ
Avalanche energy, periodic limited by T_{jmax}	E_{AR}		0.18	
Reverse diode d*v*/d*t*	d*v*/d*t*	I_D=1.9 A, V_{DS}=48 V, d*i*/d*t*=-200 A/µs, $T_{j,max}$=150 °C	-6	kV/µs
Gate source voltage	V_{GS}		±20	V
Power dissipation	P_{tot}	T_A=25 °C	1.8	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	°C
ESD class		JESD22-C101 (HBM)	1A (250V to 500V)	
Soldering temperature			260 °C	
IEC climatic category; DIN IEC 68-1			55/150/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction -soldering point	R_{thJS}		-	-	20	K/W
SMD version, device on PCB:	R_{thJA}	minimal footprint	-	-	110	K/W
		6 cm^2 cooling area[1)]	-	-	70	

Electrical characteristics, at T_j=25 °C, unless otherwise specified

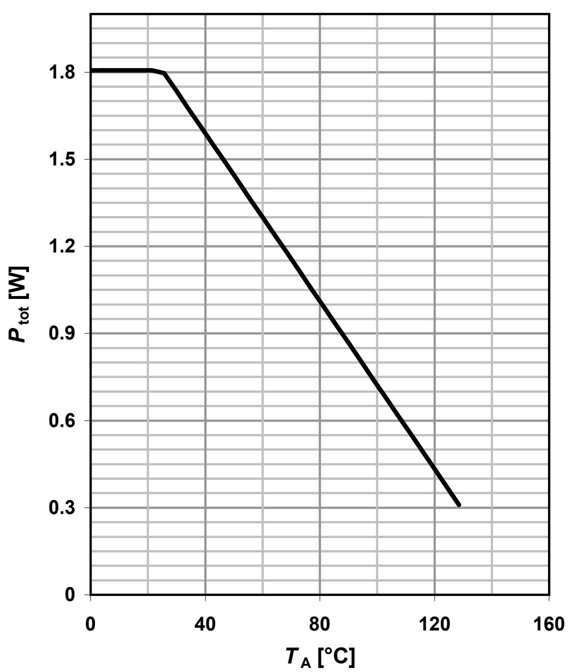
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=-250 µA	-60	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=-250 µA	-2.1	-3	-4	
Zero gate voltage drain current	I_{DSS}	V_{DS}=-60 V, V_{GS}=0 V, T_j=25 °C	-	-0.1	-1	µA
		V_{DS}=-60 V, V_{GS}=0 V, T_j=125 °C	-	-10	-100	
Gate-source leakage current	I_{GSS}	V_{GS}=-20 V, V_{DS}=0 V	-	-10	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=-10 V, I_D=-1.9 A	-	239	300	mΩ
Transconductance	g_{fs}	$\|V_{DS}\|>2\|I_D\|R_{DS(on)max}$, I_D=-1.9 A	1.3	2.6	-	S

[1)] Device on 40mm*40mm*1.5 epoxy PCB FR4 with 6cm² (one layer, 70µm thick) copper area for drain connection. PCB is vertical without blown air.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=-25 V, f=1 MHz	-	328	410	pF
Output capacitance	C_{oss}		-	105	135	
Reverse transfer capacitance	C_{rss}		-	38	48	
Turn-on delay time	$t_{d(on)}$	V_{DD}=-30 V, V_{GS}=-10 V, I_D=-1.9 A, R_G=6 Ω	-	14	21	ns
Rise time	t_r		-	28	42	
Turn-off delay time	$t_{d(off)}$		-	92	138	
Fall time	t_f		-	60	90	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	V_{DD}=-48 V, I_D=-1.9 A, V_{GS}=0 to -10 V	-	-1.4	-1.9	nC
Gate to drain charge	Q_{gd}		-	-4.9	-7.4	
Gate charge total	Q_g		-	-10	-14	
Gate plateau voltage	$V_{plateau}$		-	-4.34	-	V
Reverse Diode						
Diode continuous forward current	I_S	T_A=25 °C	-	-	-1.98	A
Diode pulse current	$I_{S,pulse}$		-	-	-7.6	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=-1.9 A, T_j=25 °C	-	-0.83	-1.1	V
Reverse recovery time	t_{rr}	V_R=30 V, I_F=|I_S|, di_F/dt=100 A/µs	-	36	54	ns
Reverse recovery charge	Q_{rr}		-	41	62	nC

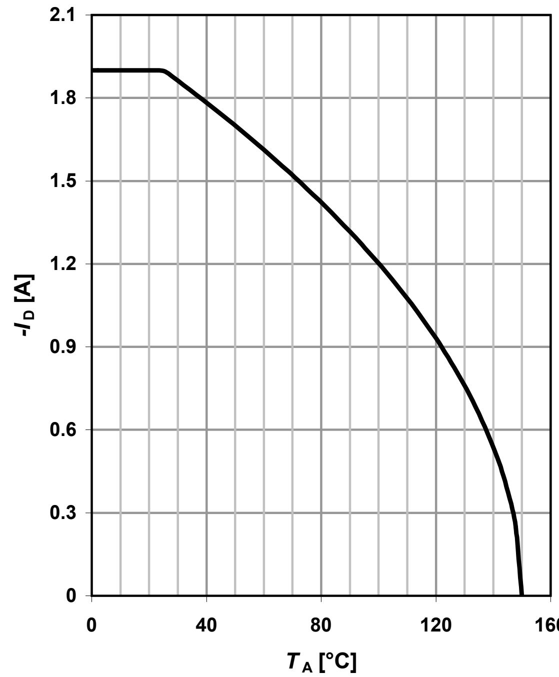
1 Power dissipation

P_{tot}=f(T_A)



2 Drain current

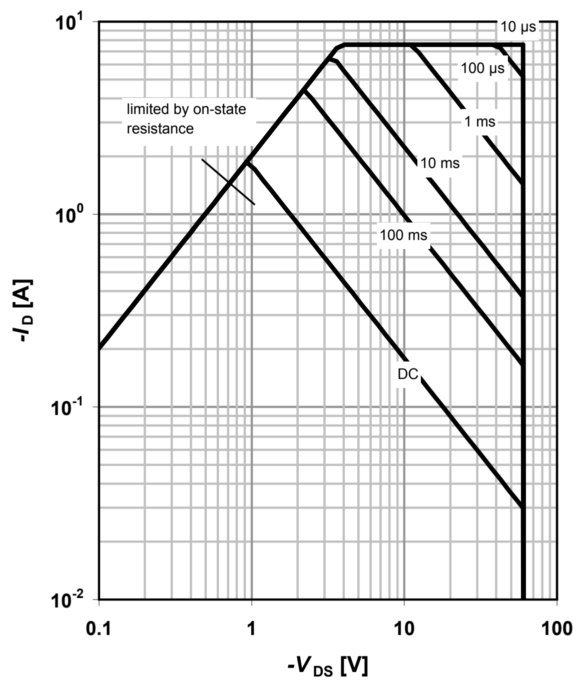
I_D=f(T_A); |V_{GS}|≥10 V



3 Safe operating area

I_D=f(V_{DS}); T_A=25 °C[1]; D=0

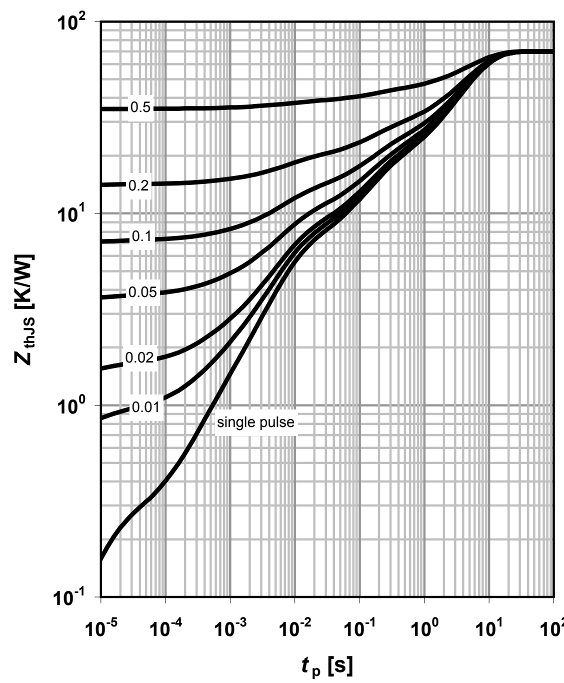
parameter: t_p



4 Max. transient thermal impedance

Z_{thJA}=f(t_p)

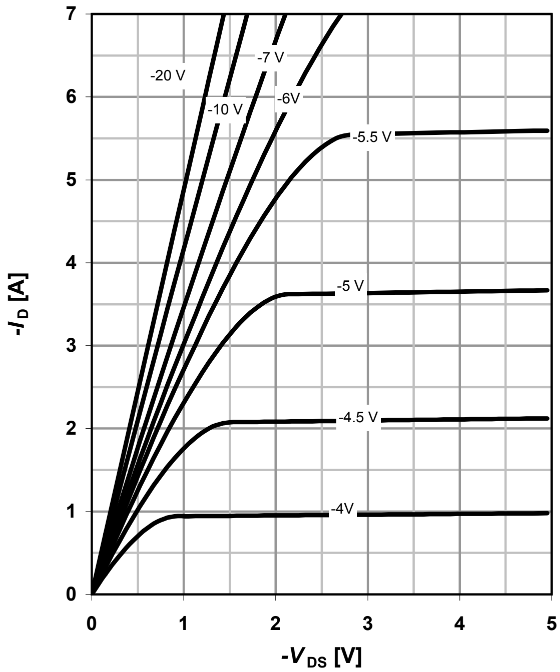
parameter: D=t_p/T



5 Typ. output characteristics

I_D=f(V_{DS}); T_j=25 °C

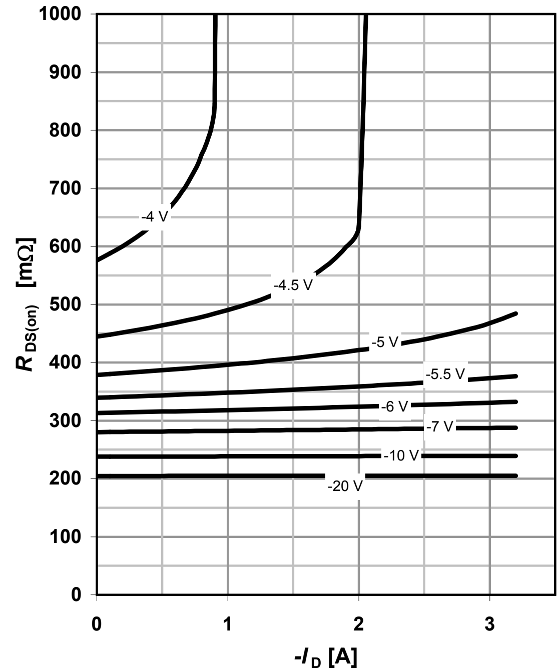
parameter: V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)}$=f(I_D); T_j=25 °C

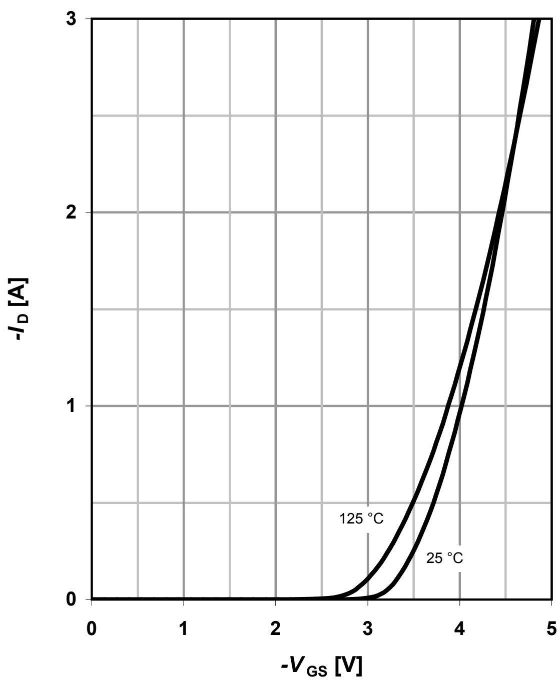
parameter: V_{GS}



7 Typ. transfer characteristics

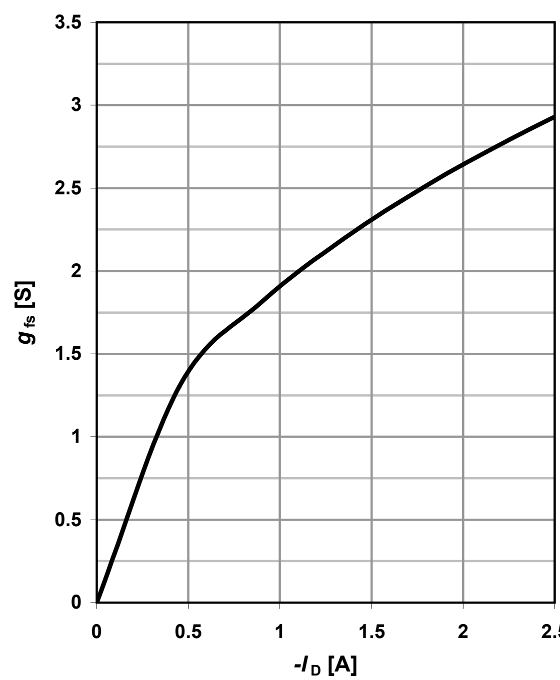
I_D=f(V_{GS}); |V_{DS}|>2|I_D|$R_{DS(on)max}$

parameter: T_j



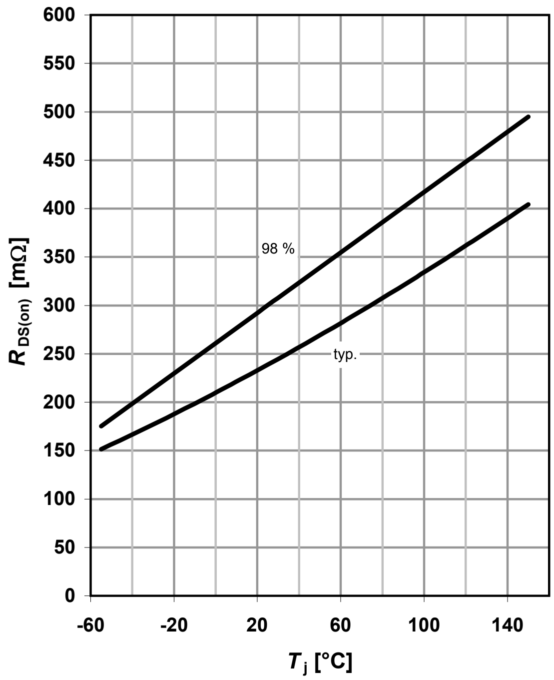
8 Typ. forward transconductance

g_{fs}=f(I_D); T_j=25 °C



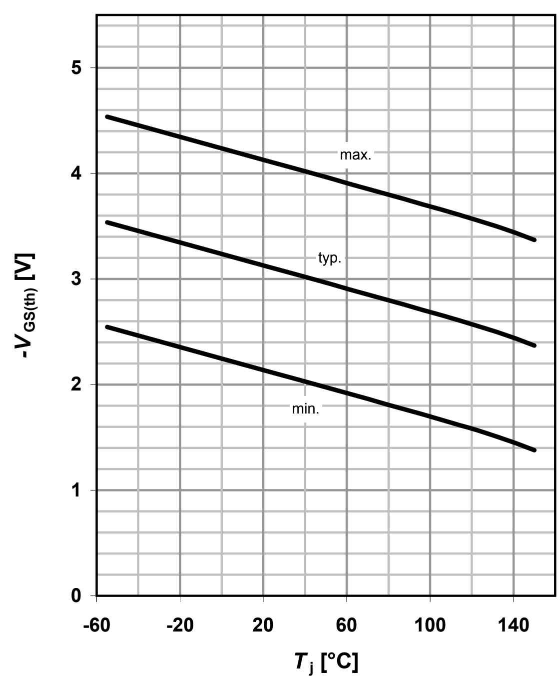
9 Drain-source on-state resistance

$R_{DS(on)}$=f(T_j); I_D=-1.9 A; V_{GS}=-10 V



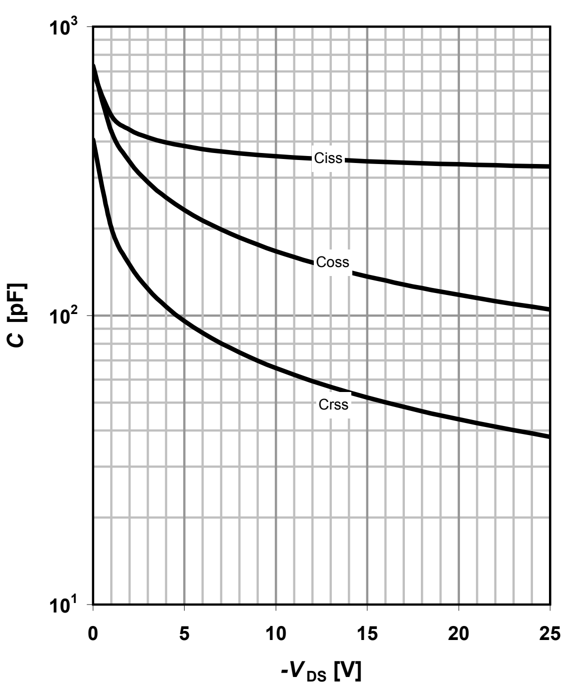
10 Typ. gate threshold voltage

$V_{GS(th)}$=f(T_j); V_{GS}=V_{DS}; I_D=-250 µA



11 Typ. capacitances

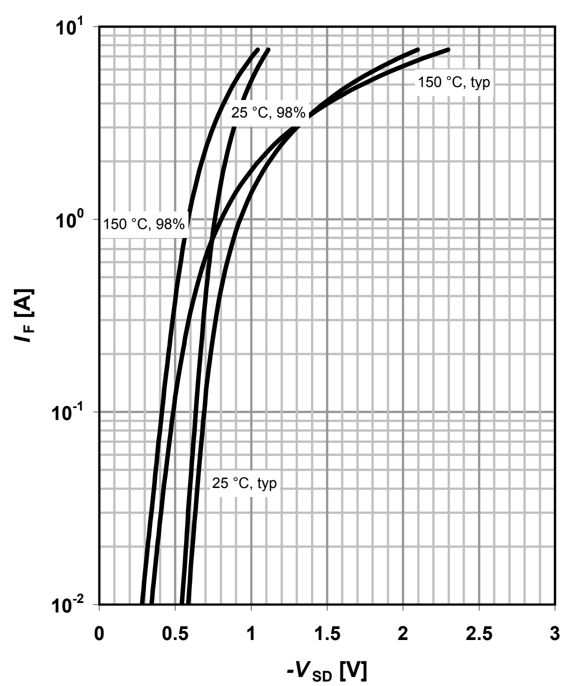
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz



12 Forward characteristics of reverse diode

I_F=f(V_{SD})

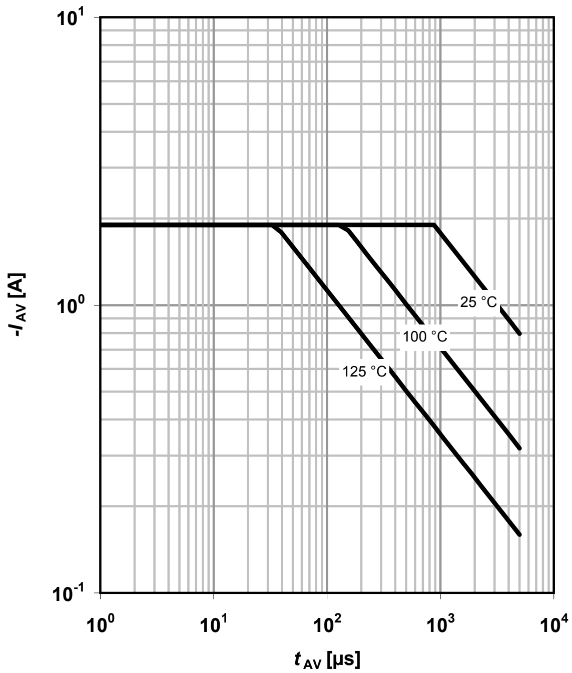
parameter: T_j



13 Avalanche characteristics

I_{AS}=f(t_{AV}); R_{GS}=25 Ω

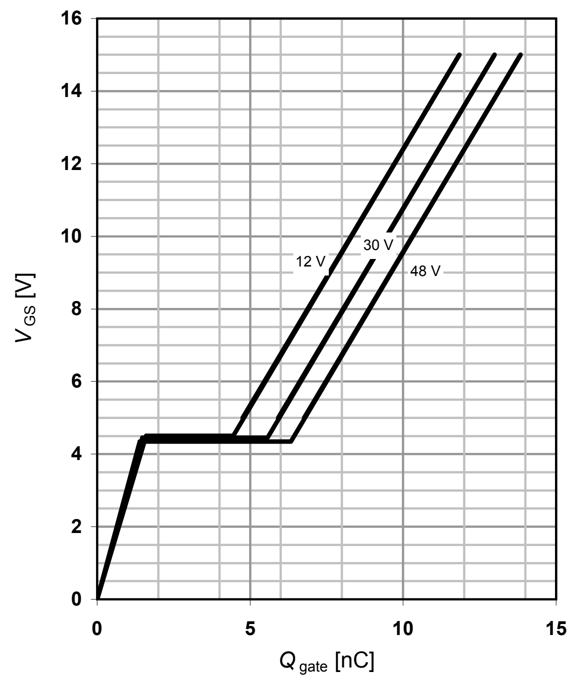
parameter: $T_{j(start)}$



14 Typ. gate charge

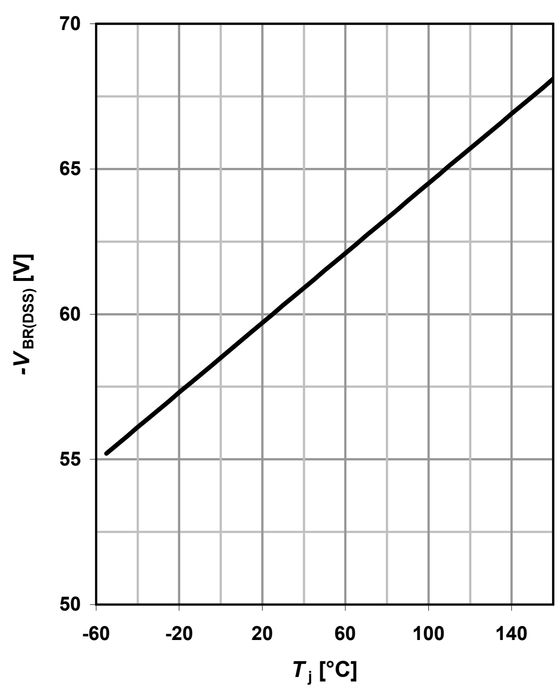
V_{GS}=f(Q_{gate}); I_D=-1.9 A pulsed

parameter: V_{DD}



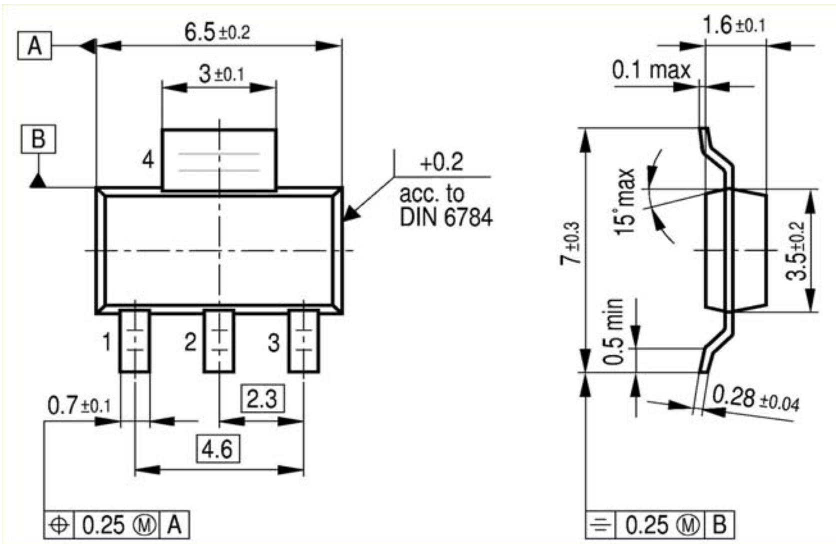
15 Drain-source breakdown voltage

$V_{BR(DSS)}$=f(T_j); I_D=-250 µA

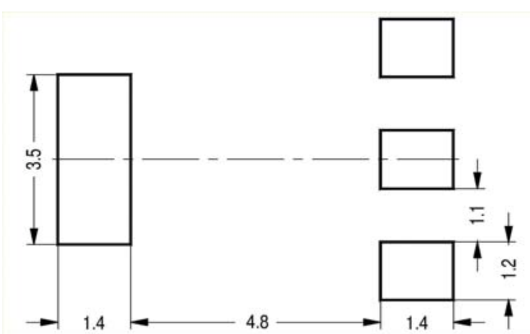


Package Outline

SOT-223: Outline

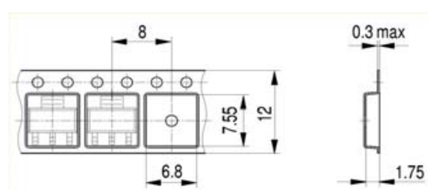


Footprint



Packaging

Tape



Dimensions in mm

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